ABSTRACT OF DISCLOSURE

A heat dissipation device having an integral load centering mechanism adapted to provide a location for contact between a spring clip and the heat dissipation device. The load centering mechanism is located in an area on the heat dissipation device which will provide a centered loading to a microelectronic die and constitutes substantially the only place where the spring clip contacts the heat dissipation device when the spring clip is providing a force against the heat dissipation device.